

02-26-2003



Patent and Trademark Office

Atty Ref/Docket No.: 303.850US1

To the Honorable Commissioner of Patents and Tradem.

102374221

Copy thereof.

1. Name of conveying party(ies):

Tongbi Jiang

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Additional name(s) of conveying party(ies) attached? [] Yes [X] No

3. Nature of conveyance:

Street Address: 8000 So. Federal Way
Boise, ID 83716-9632

[X] Assignment

[] Merger

[] Security Agreement

[] Change of Name

[] Other

Execution Date: January 29, 2003

Additional name(s) & address(es) attached? [] Yes [X] No

4. Application number(s) or patent number(s):

10365998

If this document is being filed together with a new application, the execution date of the application is: January 29, 2003

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? [] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Daniel J. Kluth

6. Total number of applications and patents involved: 1

Address: Schwegman, Lundberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

7. Total fee (37 CFR 3.41): \$ 40.00

[X] Enclosed

[] Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to our
Deposit account number: 19-0743.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Daniel J. Kluth/Reg. No. 32,146

Name of Person Signing

Daniel J. Kluth
Signature

Feb. 12, 2003

Date

Total number of pages including cover sheet: 3

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

02/25/2003 EC00PER 00000079 10365998

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40.00 DP



ASSIGNMENT

WHEREAS, I, Tongbi Jiang, residing at 12036 W. Patrina Drive, Boise, ID 83713, made certain new and useful inventions and improvements for which I executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled SEMICONDUCTOR SUBSTRATE FOR BUILD-UP PACKAGES.

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, Boise, ID 83716-9632, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I do hereby agree that I and my executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore I covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me and that full right to convey the same as herein expressed is possessed by me.

IN TESTIMONY WHEREOF, I have hereunto set my hand

this 29th day of Jan., 2003. rg.

Tongbi Jiang
Tongbi Jiang

STATE OF Idaho)
COUNTY OF Ada)ss.

On this 29th day of January, 2003 before me personally appeared Tongbi Jiang to me known and known to me to be the person described in and who executed the foregoing instrument, and he/she duly acknowledged to me that he/she executed the same for the uses and purposes therein set forth.

[SEAL] Carol A. Ketchum
Notary Public

